



OLED SPECIFICATION

Model No:

REX012864GYPP3N00F00

CUSTOMER:

APPROVED BY	
PCB VERSION	
DATE	

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APPROVAL FOR SPECIFICATIONS ONLY

oxdot APPROVAL FOR SPECIFICATIONS AND SAMPLE



1. Revision History

VERSION	DATE	REVISED PAGE NO.	Note
0	2017/06/05		First release
Α	2017/11/17		Modify Reliability test
			Condition
В	2018/11/28		Modify Static
			electricity test
			Content of Test
С	2019/09/02		Modify Precautions in
			use of OLED Modules



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- 1.General Specification
- 2. Module Classification Information
- 3.Interface Pin Function
- 4. Contour Drawing & Block Diagram
- 5. Absolute Maximum Ratings
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- 10.Inspection specification
- 11.Precautions in use of OLED Modules



1.General Specification

The Features is described as follow:

■ Module dimension: 60.5 × 37.0 × 2.15 mm

■ Active area: 55.01 × 27.49 mm

■ Dot Matrix: 128 × 64

■ Pixel Size: 0.4 × 0.4 mm

■ Pixel Pitch: 0.43 × 0.43 mm

■ Duty: 1/64 Duty

Display Mode: Passive MatrixDisplay Color: OLED , Yellow

■ IC: SSD1309Z

■ Interface: 6800,8080,SPI,I2C

■ Size: 2.42 inch



2. Module Classification information

1	2	3	4	5	6	7	8	9	10	11	12	13	14
R	Е	Х	012864	G	Y	Р	Р	3	N	0	0	F	00

1	Brand: Raystar Optronics Inc.					
2	E:OLED					
3	Display Type	C : COB Character X : COG P : COG + FR + PCB A : COG + PCB				OB Graphic OG + FR AB
4	Dot Matrix: 1	28*64				
5	Series				•	
6	Emitting Color A: Amber B: Blue G: Green S: Sky Blue			R: Red W: White Y: Yellow X: Dual Color		C : Full Color
7	Polarizer Polarizer A: Anti-glare Polarizer					
8	Display Mode)	P: Passive Matrix;	; N: Active Matri	X	
9	Driver Voltage			: 5.0V		
10	Touch Panel		N: Without touch p	anel; T: With toud	ch pane	el
11	Product type	0 : Standard 1 : Daylight Readable				
12	Inspection Gra	de	0 : Standard 2 : B grade C : Automotive grade Y : Consumer grade 0 : Default ; F : ZIF FPC ; H : Hot bar FPC; D : Demo Kit			
13	Option				ar FPC	; D : Demo Kit
14	Serial No.		Serial number(00~2	<u> </u>		1600000



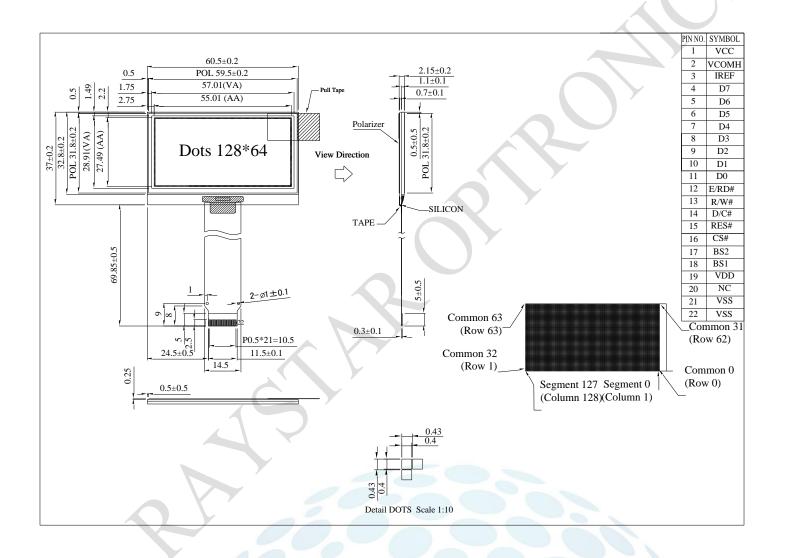
3. Interface Pin Function

No.	Symbol	Function						
1	VCC	Power su	ipply fo	or analog circuit.				
2	VCОМН		Com Voltage Output. A capacitor should be connected between this pin and VSS.					
3	IREF		Reference current input pin. A resistor should be connected between this pin and VSS.					
4~11	D7~D0	Data bus			7			
12	E/RD#	Data read	d opera	ation is initiated v	when it's pull low.			
13	R/W#	Data writ	e oper	ation is initiated	when it's pull low.			
14	D/C#		for wri	d control. te/read display c e command or re				
15	RES#	Reset sig When it's			SD1305 is executed	d.		
16	CS#	Chip sele	ect inpu	ut.				
17	BS2		ns are	Protocol Select MCU interface s	election input. See	the		
		Tollowing	I2C	68XX-parallel	80XX-parallel	Serial		
18	BS1	BS1	1	0	1	0		
		BS2	0	1	1	0		
10	VDD	Power supply for logic circuit.						
19	VDD	No conne		or logic circuit.				
20	NC		ecuon.					
21	VSS	Ground.						
22	VSS	Ground.	Ground.					

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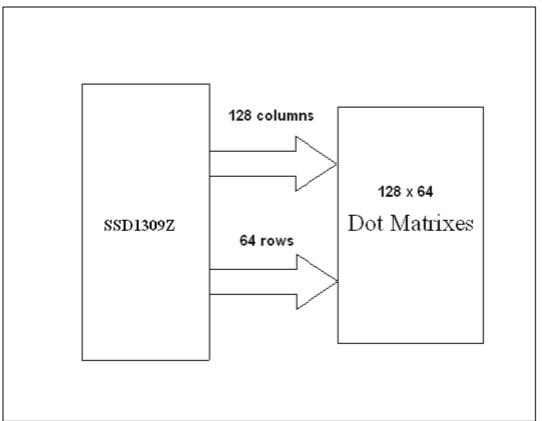


4. Contour Drawing & Block Diagram





FUNCTION BLOCK DIAGRAM



^{*}For more information, please refer to Application Note provided by Raystar Optronics.





5. Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit	Notes
Supply Voltage for Logic	VDD	-0.3	4	V	1, 2
Supply Voltage for Display	VCC	0	15	V	1, 2
Operating Temperature	TOP	-40	+80	ŷ	-
Storage Temperature	TSTG	-40	+85	°C	-

Note 1: All the above voltages are on the basis of "VSS = 0V".

Note 2: When this module is used beyond the above absolute maximum ratings, permanent breakage of the module may occur. Also, for normal operations, it is desirable to use this module under the conditions according to Section 6 "Electrical Characteristics". If this module is used beyond these conditions, malfunctioning of the module can occur and the reliability of the module may deteriorate



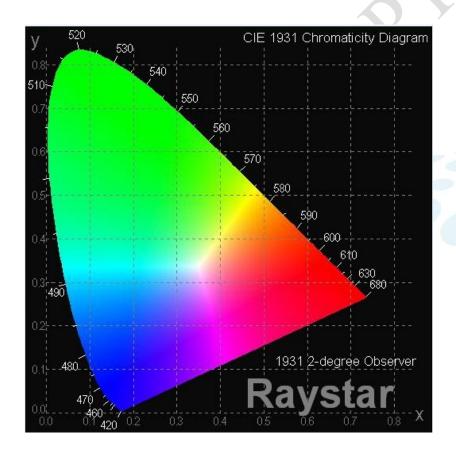
6.Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage for Logic	VDD	_	2.8	3.0	3.3	V
Supply Voltage for Display	VCC	_	12.5	13.0	13.5	V
High Level Input	VIH	_	0.8×VDD	_	VDD	V
Low Level Input	VIL	_	0		0.2×VDD	V
High Level Output	VOH	_	0.9×VDD	+	VDD	V
Low Level Output	VOL	_	0	1	0.1×VDD	V
50% Check Board operatir Current	ng	VCC =13V	15	18	22	mA



7. Optical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
View Angle	(V)θ	_	160	_		deg
	(Η)φ	_	160	_	1	deg
Contrast Ratio	CR	Dark	2000:1	7	-)	
Response Time	T rise	_		10		μs
	T fall	_	-	10	_	μs
Display with 50% check	Board Brig	htness	70	90	_	cd/m2
CIEx(Yellow)		(CIE1931)	0.45	0.47	0.49	_
CIEy(Yellow)		(CIE1931)	0.48	0.50	0.52	_





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8.OLED Lifetime

ITEM	Conditions	Min	Тур	Remark
Operating Life Time	Ta=25°C / Initial 50% check board brightness Typical Value	50,000 Hrs	-	Note

Notes:

- 1. Life time is defined the amount of time when the luminance has decayed to <50% of the initial value.
- 2. This analysis method uses life data obtained under accelerated conditions to extrapolate an estimated probability density function (*pdf*) for the product under normal use conditions.
- 3. Screen saving mode will extend OLED lifetime.



9.Reliability

Content of Reliability Test

Environmenta Test Item	Content of Test	Test Condition	Applicable
High Temperature storage	Endurance test applying the high storage temperature for a long time.	85℃ 240hrs	Standard
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-40°C 240hrs	-
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	80℃ 240hrs	
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-40℃ 240hrs	
High Temperature/ Humidity Storage	Endurance test applying the high temperature and high humidity storage for a long time.	60℃,90%RH 240hrs	
High Temperature/ Humidity Operation	Endurance test applying the high temperature and high humidity Operation for a long time.	60℃,90%RH 120hrs	
Temperature Cycle	Endurance test applying the low and high temperature cycle. -40°C 25°C 80°C 30min 5min 30min 1 cycle	-40°C/80°C 30 cycles	
Mechanical Tes	st C		
Vibration test	Endurance test applying the vibration during transportation and using.	Frequency:10~55Hz amplitude:1.5mm Time:0.5hrs/axis Test axis:X,Y,Z	
Others			
Static electricity test	Endurance test applying the electric stress to the finished product housing.	Air Discharge model ±4kv,10 times	

^{***} Supply voltage for OLED system =Operating voltage at 25 $^{\circ}\mathrm{C}$



Test and measurement conditions

- 1. All measurements shall not be started until the specimens attain to temperature stability. After the completion of the described reliability test, the samples were left at room temperature for 2 hrs prior to conducting the failure test at 23±5°C; 55±15% RH.
- 2. All-pixels-on is used as operation test pattern.
- 3. The degradation of Polarizer are ignored for High Temperature storage, High Temperature/ Humidity Storage, Temperature Cycle

Evaluation criteria

- 1. The function test is OK.
- 2. No observable defects.
- 3. Luminance: > 50% of initial value.
- 4. Current consumption: within ± 50% of initial value.

APPENDIX:

RESIDUE IMAGE

Because the pixels are lighted in different time, the luminance of active pixels may reduce or differ from inactive pixels. Therefore, the residue image will occur. To avoid the residue image, every pixel needs to be lighted up uniformly.



10.Inspection specification

NO	Item	Criterion					AQL		
01	Electrical	1.1 Missing verti	1.1 Missing vertical, horizontal segment, segment contrast						
	Testing	defect.							
		_	1.2 Missing character, dot or icon.						
		1.3 Display malf							
		1.4 No function					0.65		
		1.5 Current cons				ecifications.			
		1.6 OLED viewir 1.7 Mixed produ		ereci					
		1.8 Contrast def	<i>,</i> ,						
		1.0 001111431 401	001.						
02	Black or	2.1 White and b	ack spots	on d	isplay ≦0.25r	mm, no more than			
	white	three white or bl				(
	spots on	2.2 Densely spa	ced: No m	ore t	han two spots	or lines within	2.5		
	OLED	3mm.					2.0		
	(display								
03	only) OLED	2.1 Dound tupo	. ^ _						
03	black	3.1 Round type following drawin			SIZE	Acceptable Q			
	spots,	$\Phi = (x + y)/2$	9		OIZL	TY			
	white	Y .			Ф≦0.10	Accept no			
	spots,	·→∍î·≉⊷↓) = 00	dense			
	contamina	• •	v		0.10<	2	2.5		
	tion	7		,	Ф≦0.20				
	(non-displ			Ī	0.20<	1			
	ay)				Ф≦0.25				
					0.25<Ф	0			
		3.2 Line type : (/	As followin	g dra	awing)		0		
			Length	Wid		Acceptable Q TY			
		$\sim 1 \frac{v}{v}$		W	≦0.02	Accept no dense			
		→	L≦3.0	0.0	2 <w≦0.03< td=""><td>2</td><td>2.5</td></w≦0.03<>	2	2.5		
			L≦2.5	0.0	3 <w≦0.05< td=""><td>2</td><td></td></w≦0.05<>	2			
				0.0	5 <w< td=""><td>As round type</td><td></td></w<>	As round type			
04	Polarizer	10							
	bubbles		If bubbles are visible, Size Φ Acceptable Q TY						
	7	, ,	udge using black spot Φ≦0.20 Accept no dense						
		specifications, n		0.2	.0<Φ≦0.50	3	2.5		
		to find, must che specify direction		0.5	50<Φ≦1.00	2	0.6		
		specify difection	•	1.0	0<Ф	0			
				Tot	al Q TY	3 /00			



NO	Item	Criterion		AQL	
05	Scratches	Follow NO.3 OLED black spots, white spots, contamination			
	Chipped glass		: Glass thickness a: th:	Chip thickness OLED side length	
		6.1.1 Chip on panel s		ween panels:	
			A CANADA		
		z: Chip thickness	y: Chip width	x: Chip length	
		Z≦1/2t	Not over viewing	x≤1/8a	
06		4/04 < - < 04	area	< 4/0 -	2.5
		$1/2t < z \le 2t$	Not exceed 1/3k	x≤1/8a	
		⊙ If there are 2 or mo 6.1.2 Corner crack:	re chips, x is total len	gin of each chip.	
		z: Chip thickness	y: Chip width	x: Chip length	
	4	Z≦1/2t	Not over viewing area	x≦1/8a	5
		1/2t < z ≤ 2t	Not exceed 1/3k	x≦1/8a	
⊙ If there are 2 or more chips, x is the total length of each chip.					



NO	Item	Criterion	AQL	
		Symbols:		
		x: Chip length y: Chip width z: Chip thickness		
		k: Seal width t: Glass thickness a: OLED side length		
		L: Electrode pad length		
		6.2 Protrusion over terminal : 6.2.1 Chip on electrode pad :		
		6.2.1 Grilp Gir electrode pad .		
		VA Z)	
		V X		
		y: Chip width x: Chip length z: Chip thickness		
		$y \le 0.5 \text{mm}$ $x \le 1/8 \text{a}$ $0 < z \le t$		
		6.2.2 Non-conductive portion:		
06	Glass	* XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	2.5	
	crack	Y AZ Y AZ	2.0	
		X		
		y: Chip width x: Chip length z: Chip		
		thickness		
		$y \le L$ $x \le 1/8a$ $0 < z \le t$		
		⊙ If the chipped area touches the ITO terminal, over 2/3 of the ITO		
		must remain and be inspected according to electrode terminal		
		specifications.		
		⊙If the product will be heat sealed by the customer, the alignment		
		mark not be damaged. 6.2.3 Substrate protuberance and internal crack.		
		Υ .		
		$\begin{array}{c cccc} y: \text{ width} & x: \text{ length} \\ y \leq 1/3L & x \leq a \end{array}$		
		$y \le 1/3L$ $x \le a$		
	V -	у		
			000	



NO	Item	Criterion	AQL
07	Cracked glass	The OLED with extensive crack is not acceptable.	2.5
08	Backlight elements	 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using OLED spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. 	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.9.2 Bezel must comply with job specifications.	2.5 0.65
10	PCB、COB	 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, OLED pad, zebra pad or screw hold pad, make sure it is smoothed down. 	2.5 2.5 0.65 2.5 2.5 0.65 2.5
11	Soldering	 11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB. 	2.5 2.5 2.5 0.65



NO	Item	Criterion	AQL
		12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.	2.5
		12.2 No cracks on interface pin (OLB) of TCP.	0.65
		12.3 No contamination, solder residue or solder balls on	2.5
		product.	2.5
		12.4 The IC on the TCP may not be damaged, circuits.	2.5
		12.5 The uppermost edge of the protective strip on the	
12	General	interface pin must be present or look as if it cause the interface pin to sever.	2.5
12	appearance	12.6 The residual rosin or tin oil of soldering (component or	2.5
		chip component) is not burned into brown or black color.	0.65
		12.7 Sealant on top of the ITO circuit has not hardened.	0.65
		12.8 Pin type must match type in specification sheet.	0.65
		12.9 OLED pin loose or missing pins.	
		12.10 Product packaging must the same as specified on packaging specification sheet.	0.65
		12.11 Product dimension and structure must conform to product specification sheet.	



Check Item	Classification	Criteria			
No Display	Major				
Missing Line	Major				
Pixel Short	Major				
Darker Short	Major				
Wrong Display	Major				
Un-uniform B/A x 100% < 70% A/C x 100% < 70%	Major	A Normal B Dark Pixel C Light Pixel			



11.Precautions in use of OLED Modules

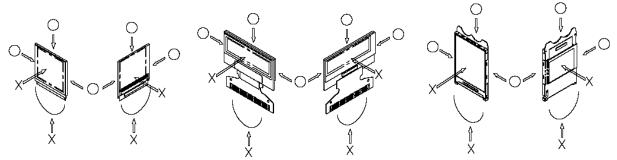
- (1) Avoid applying excessive shocks to module or making any alterations or modifications to it.
- (2) Don't make extra holes on the printed circuit board, change the components or modify its shape of OLED display module.
- (3) Don't disassemble the OLED display module.
- (4) Do not apply input signals while the logic power is off.
- (5) Don't operate it above the absolute maximum rating.
- (6) Don't drop, bend or twist OLED display module.
- (7) Soldering: only to the I/O terminals.
- (8) Hot-Bar FPC soldering condition: 280~350C, less than 5 seconds.
- (9) Raystar has the right to change the passive components (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.) and change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Raystar have the right to modify the version.)
- (10) Raystar has the right to upgrade or modify the product function.

11.1. Handling Precautions

- (1) Since the display panel is being made of glass, do not apply mechanical impacts such as dropping from a high position.
- (2) If the display panel is broken by some accident and the internal organic substance leaks out, be careful not to inhale nor lick the organic substance.
- (3) If pressure is applied to the display surface or its neighborhood of the OLED display module, the cell structure may be damaged. So, be careful not to apply pressure to these sections.
- (4) The polarizer covering the surface of the OLED display module is soft and easily scratched.
- (5) When the surface of the polarizer of the OLED display module has soil, clean the surface. It takes advantage by using following adhesion tape.
 - * Scotch Mending Tape No. 810 or an equivalent
 - Never try to breathe upon the soiled surface nor wipe the surface using cloth containing solvent such as ethyl alcohol, since the surface of the polarizer will become cloudy.
 - Also, pay attention that the following liquid and solvent may spoil the polarizer:
 - * Water
 - * Ketone
 - * Aromatic Solvents
- (6) Protection film is being applied to the surface of the display panel and removes the protection film before assembling it. At this time, if the OLED display module has been stored for a long period of time, residue adhesive material of the protection film may remain on the surface of the display panel after removed of the film. In such case, remove the residue material by the method introduced in the above Section 5.
- (7) Do not touch the following sections whenever possible while handling the OLED display modules.
 - * Pins and electrodes
 - * Pattern layouts such as the TCP & FPC
- (8) Hold OLED display module very carefully when placing OLED display module into the



System housing. Do not apply excessive stress or pressure to OLED display module. And, do not over bend the film with electrode pattern layouts. These stresses will influence the display performance. Also, secure sufficient rigidity for the outer cases.



- (9) Do not apply stress to the LSI chips and the surrounding molded sections.
- (10) Pay sufficient attention to the working environments when handing OLED display modules to prevent occurrence of element breakage accidents by static electricity.
 - * Be sure to make human body grounding when handling OLED display modules.
 - * Be sure to ground tools to use or assembly such as soldering irons.
 - * To suppress generation of static electricity, avoid carrying out assembly work under dry environments.
 - * Protective film is being applied to the surface of the display panel of the OLED display module. Be careful since static electricity may be generated when exfoliating the protective film.

11.2. Storage Precautions

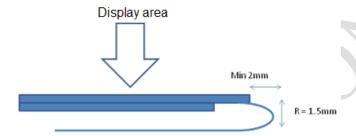
- (1) When storing OLED display modules, put them in static electricity preventive bags to avoid be directly exposed to sun or lights of fluorescent lamps. (We recommend you to store these modules in the packaged state when they were shipped from Raystar. At that time, be careful not to let water drops adhere to the packages or bags.)
- (2) When the OLED display module is being dewed or when it is placed under high temperature or high humidity environments, the electrodes may be corroded if electric current is applied. Please store it in clean environment.

11.3. Designing Precautions

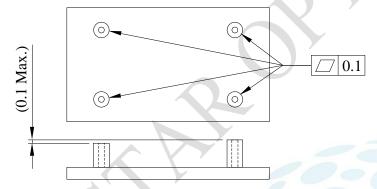
- (1) The absolute maximum ratings are the ratings which cannot be exceeded for OLED display module, and if these values are exceeded, OLED display module may be damaged.
- (2) To prevent occurrence of malfunctioning by noise, pay attention to satisfy the VIL and VIH specification and to make the signal line cable as short as possible.
- (3) We recommend you to install excess current preventive unit (fuses, etc.) to the power circuit (VDD / VCC). (Recommend value: 0.5A)
- (4) Pay sufficient attention to avoid occurrence of mutual noise interference with the nearby devices.
- (5) As for EMI, take necessary measures on the equipment side basically.
- (6) If the power supplied to the OLED display module is forcibly shut down by such errors as taking out the main battery while the OLED display panel is in operation, we cannot guarantee the quality of this OLED display module.
 - * Connection (contact) to any other potential than the above may lead to rupture of the IC.



- (7) If this OLED driver is exposed to light, malfunctioning may occur and semiconductor elements may change their characteristics.
- (8) The internal status may be changed, if excessive external noise enters into the module. Therefore, it is necessary to take appropriate measures to suppress noise generation or to protect module from influences of noise on the system design.
- (9) We recommend you to make periodical refreshment of the operation statuses (re-setting of the commands and re-transference of the display data) to cope with catastrophic noise.
- (10) It's pretty common to use "Screen Saver" to extend the lifetime and Don't use the same image for long time in real application. When an OLED display module is operated for a long of time with fixed pattern, an afterimage or slight contrast deviation may occur.
- (11) The limitation of FPC and Film bending.



(12) The module should be fixed balanced into the housing, or the module may be twisted.



11.4. Precautions when disposing of the OLED display modules

(1) Request the qualified companies to handle industrial wastes when disposing of the OLED display modules. Or, when burning them, be sure to observe the environmental and hygienic laws and regulations.





Page: 1

Module Sample Estimate Feedback Sheet			
Module Number:			
1 · Panel Specification :			
1. Panel Type:	□ Pass	□NG ,	
2. Numbers of Pixel:	□ Pass	□NG ,	
3. View Area:	□ Pass	□NG ,	
4. Active Area:	□ Pass	□NG ,	
5.Emitting Color:	□ Pass	□NG ,	
6.Uniformity:	□Pass	□NG ,	
7.Operating	□ Pass	□NG ,	
Temperature :			
8.Storage Temperature:	□ Pass	□NG ,	
9.Others:	1		
2 · Mechanical Specificati	<u>on</u> :		
1. PCB Size :	□Pass	□NG ,	
2.Frame Size :	□Pass	□NG ,	
3.Materal of Frame:	□Pass	□NG ,	
4.Connector Position:	□Pass	□NG ,	
5.Fix Hole Position:	□Pass	□NG ,	
6. Thickness of PCB:	□Pass	□NG ,	
7. Height of Frame to	□Pass	□NG ,	
PCB:			
8.Height of Module:	□Pass	□NG ,	
9.Others:	□Pass	□NG ,	
3 · Relative Hole Size :			
1.Pitch of Connector:	□Pass	□NG ,	
2.Hole size of	□Pass	□NG ,	
Connector:			
3.Mounting Hole size:	□Pass	□NG ,	
4.Mounting Hole Type:	□Pass	□NG ,	
5 Others :	□Pass	⊓NG	

>> Go to page 2 <<



Manhala Namalas a		Page: 2	
Module Number :			
4 · Electronic Characteristics of Module :			
1.Input Voltage:	□Pass	□NG ,	
2.Supply Current:	□Pass	□NG ,	
3.Driving Voltage for OLED:	□Pass	ING ,	
4.Contrast for OLED:	□Pass	□NG ,	
5.Negative Voltage Output:	□Pass	□NG ,	
6.Interface Function:	□Pass	□NG ,	
7.ESD test:	□Pass	□NG ,	
8.Others:	□Pass	□NG ,	
Sales signature : Customer Signature	• :		